

MECHANICAL CASE OUTLINE

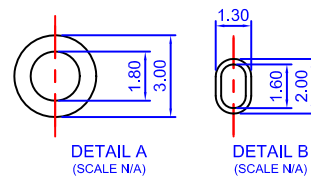
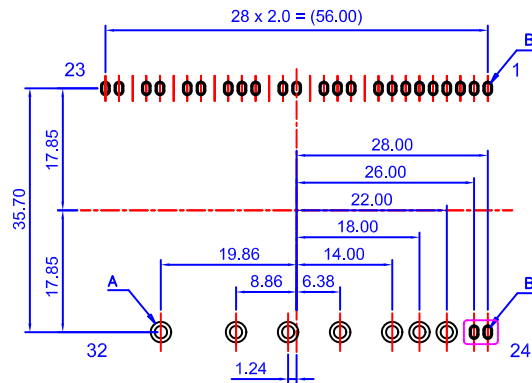
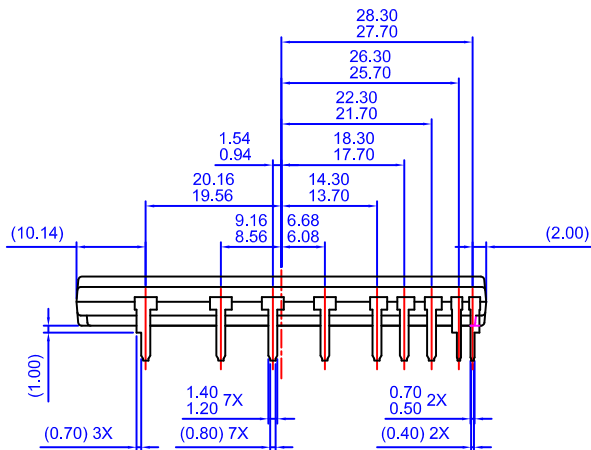
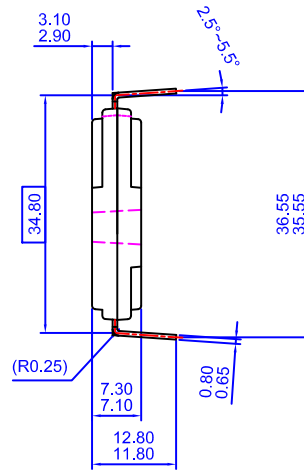
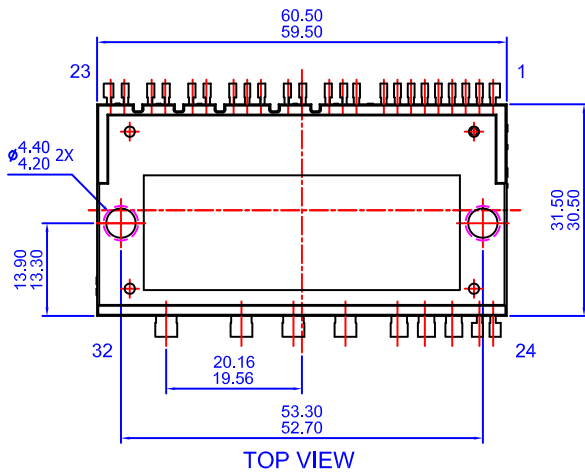
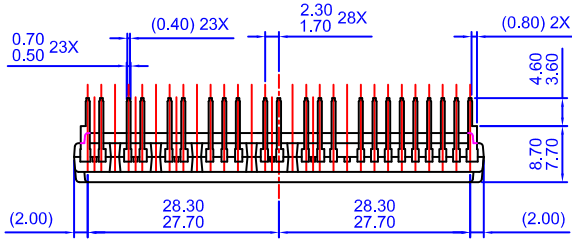
PACKAGE DIMENSIONS

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S32CA-032 / 32LD, PDD STD, DBC, DIP TYPE (DBC AIN) CASE MODEB ISSUE O

DATE 31 JAN 2017



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